



Patent



Customer No. 31561  
Application No.: 10/063,793  
Docket No. 8192-US-PA

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Applicant : Chen et al.  
Application No. : 10/063,793  
Filed : May 14, 2002  
For : INTEGRATED CIRCUIT PACKAGE AND METHOD OF  
MANUFACTURE  
Examiner : N/A  
Art Unit : 2841

**RESUBMITTING PRIORITY DOCUMENT**

**002-1-703-305-5582**

**(Via fax: 1+ 38 pages)**

**Ms. Shirley Steele**

U.S. Patent and Trademark Office  
2900 Crystal Drive 22202, Mail Stop Duplicates

Dear Ms. Steele,

Per your request, resubmitted herewith is the priority document of Taiwan application no. 91100554 for the above-identified application, originally filed with the Office on August 27, 2002.

Thank you for your kind attention to this regard. Should you need further information, please feel free to contact the undersigned.

Respectfully Submitted,  
JIANQ CHYUN Intellectual Property Office

Dated: April 14, 2005

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